

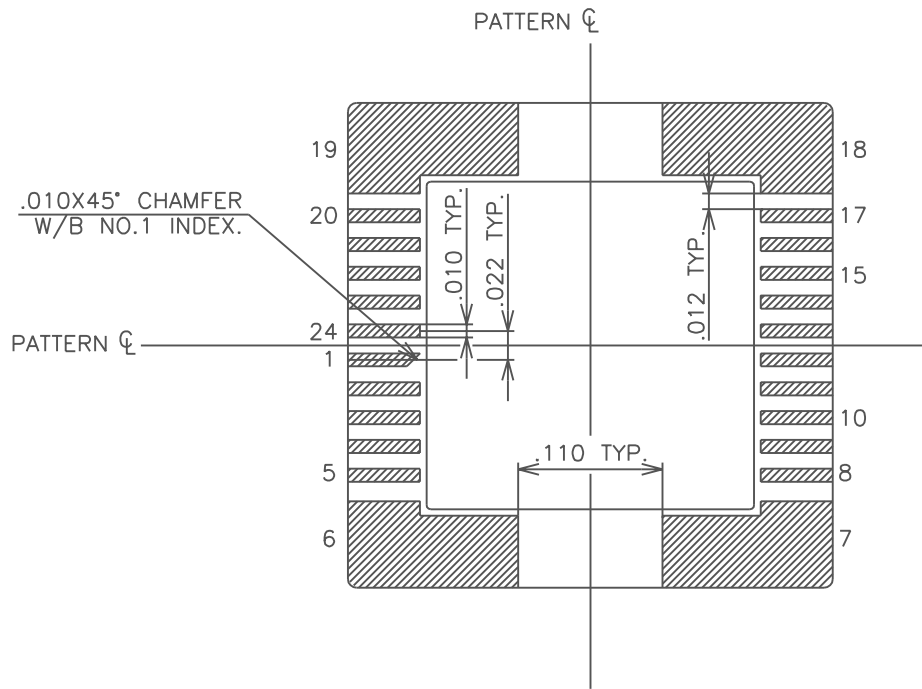
NOTES

1. GOLD PLATING 60 MICRO INCHES MIN. THICKNESS OVER 100 MICRO INCHES NOMINAL THICKNESS OF NICKEL. UNLESS OTHERWISE SPECIFIED IN PURCHASE ORDER.
2. DIE ATTACH PAD AND SEAL RING TO BE FLOATING FROM ANY PINS.
3. LEAD RESISTANCE : 0.5 OHM MAX.

SB024L036-1				S=0 D=0
DRAWN	CHECKED	APPROVED	DATE	
H.K	K.M		FEB.3.8	
DRAWING NO.				SHEET
KD-S81036-A				1/2

MODIFICATION						NAME	TOLERANCE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED
						SCALE 4 / 1	MATERIAL
							AS INDICATED
							±.005
							THIRD ANGLE PROJECTION
△	REDRAWN : CONVERTED CAD DATA.	MAY.7.'01	T.S/H.K	SH.K/S.NI	H.SA	KYOCERA CORPORATION	
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	KYOTO JAPAN	





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						24 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	H.K	K.M		FEB.3.'8
						SCALE 10 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
△	REDRAWN : CONVERTED CAD DATA.	MAY.7.'01	T.S./H.K	SH.K./S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-S81036-A	SHEET
	CHANGED	DATE	DRAWN	CHECKED	APPROVED			2 / 2			